

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.42366	100.0	6.1
			<b>Subtotal</b>	<b>0.42366</b>	<b>100</b>	<b>6.1</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.15835	100.0	2.28
			<b>Subtotal</b>	<b>0.15835</b>	<b>100</b>	<b>2.28</b>
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.73632	100.0	25
			<b>Subtotal</b>	<b>1.73632</b>	<b>100</b>	<b>25</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02334	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.05834	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	58.25858	99.86	838.824
			<b>Subtotal</b>	<b>58.34026</b>	<b>100</b>	<b>840</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.39884	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.25074	16.0	90
	Filler	Silica fused	60676-86-0	29.30035	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.1172	0.3	1.6875
			<b>Subtotal</b>	<b>39.06713</b>	<b>100</b>	<b>562.5</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.0132	5.0	0.19
	Lead alloy	Silver (Ag)	7440-22-4	0.0066	2.5	0.095
	Lead alloy	Lead (Pb)	7439-92-1	0.24413	92.5	3.515
			<b>Subtotal</b>	<b>0.26393</b>	<b>100</b>	<b>3.8</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01036	100.0	0.1491
			<b>Subtotal</b>	<b>0.01036</b>	<b>100</b>	<b>0.1491</b>
			<b>Total</b>	<b>100.00001</b>	<b>100</b>	<b>1439.8291</b>

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